

74AUP1G34

Low-power buffer

Rev. 8 — 8 June 2018

Product data sheet

1 General description

The 74AUP1G34 provides a low-power, low-voltage single buffer.

Schmitt trigger action at all inputs makes the circuit tolerant to slower input rise and fall times across the entire V_{CC} range from 0.8 V to 3.6 V.

This device ensures a very low static and dynamic power consumption across the entire V_{CC} range from 0.8 V to 3.6 V.

This device is fully specified for partial power-down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

2 Features and benefits

- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- Complies with JEDEC standards:
 - JESD8-12 (0.8 V to 1.3 V)
 - JESD8-11 (0.9 V to 1.65 V)
 - JESD8-7 (1.2 V to 1.95 V)
 - JESD8-5 (1.8 V to 2.7 V)
 - JESD8-B (2.7 V to 3.6 V)
- ESD protection:
 - HBM: ANSI/ESDA/JEDEC JS-001 Class 3A exceeds 5000 V
 - CDM: ANSI/ESDA/JEDEC JS-002 Class C3 exceeds 1000 V
 - MM: JESD22-A115-A exceeds 200 V
- Low static power consumption; $I_{CC} = 0.9 \mu A$ (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10 % of V_{CC}
- I_{OFF} circuitry provides partial power-down mode operation
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

nexperia

3 Ordering information

Table 1. Ordering information

Type number	Package				Version
	Temperature range	Name	Description		
74AUP1G34GW	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm		SOT353-1
74AUP1G34GM	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm		SOT886
74AUP1G34GF	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm		SOT891
74AUP1G34GN	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 x 1.0 x 0.35 mm		SOT1115
74AUP1G34GS	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 x 1.0 x 0.35 mm		SOT1202
74AUP1G34GX	-40 °C to +125 °C	X2SON5	plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 x 0.8 x 0.35 mm		SOT1226
74AUP1G34GX4	-40 °C to +125 °C	X2SON4	plastic thermal enhanced extremely thin small outline package; no leads; 4 terminals; body 0.6 x 0.6 x 0.32 mm		SOT1269-2
74AUP1G34UK	-40 °C to +125 °C	WLCSP6	wafer level chip-scale package; 6 bumps; 0.65 x 0.44 x 0.27 mm		SOT1454-1

4 Marking

Table 2. Marking

Type number	Marking code ^[1]
74AUP1G34GW	aN
74AUP1G34GM	aN
74AUP1G34GF	aN
74AUP1G34GN	aN
74AUP1G34GS	aN
74AUP1G34GX	aN
74AUP1G34GX4	aN
74AUP1G34UK	4

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5 Functional diagram

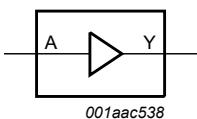


Figure 1. Logic symbol



Figure 2. IEC logic symbol

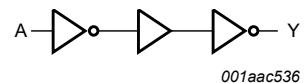


Figure 3. Logic diagram

6 Pinning information

6.1 Pinning

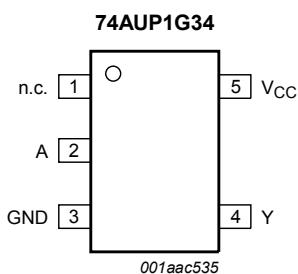


Figure 4. Pin configuration SOT353-1 (TSSOP5)

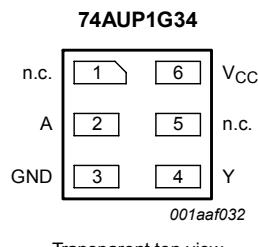


Figure 5. Pin configuration SOT886, SOT891, SOT1115 and SOT1202 (XSON6)

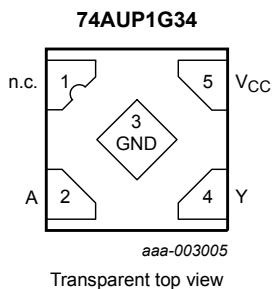


Figure 6. Pin configuration SOT1226 (X2SON5)

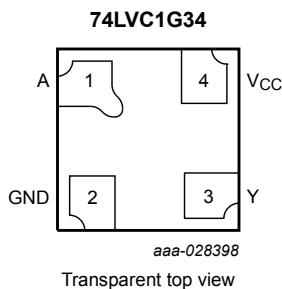


Figure 7. Pin configuration SOT1269-2 (X2SON4)

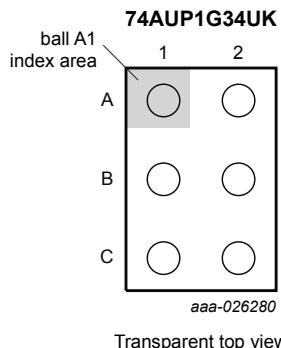


Figure 8. Pin configuration SOT1454-1 (WLCSP6)

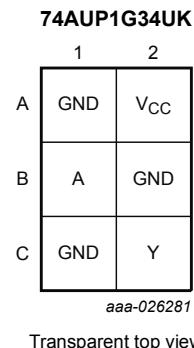


Figure 9. Ball mapping for SOT1454-1 (WLCSP6)

6.2 Pin description

Table 3. Pin description

Symbol	Pin				Description
	TSSOP5 and X2SON5	XSON6	X2SON4	WLCSP6	
n.c.	1	1	-	-	not connected
A	2	2	1	B1	data input
GND	3	3	2	A1, B2, C1	ground (0 V)
Y	4	4	3	C2	data output
n.c.	-	5	-	-	not connected
V _{CC}	5	6	4	A2	supply voltage

7 Functional description

Table 4. Function table

H = HIGH voltage level; L = LOW voltage level.

Input	Output
A	Y
L	L
H	H

8 Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit	
V _{CC}	supply voltage		-0.5	+4.6	V	
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA	
V _I	input voltage		[1]	-0.5	+4.6	V
I _{OK}	output clamping current	V _O < 0 V	-50	-	mA	
V _O	output voltage	Active mode and Power-down mode	[1]	-0.5	+4.6	V
I _O	output current	V _O = 0 V to V _{CC}	-	±20	mA	
I _{CC}	supply current		-	+50	mA	
I _{GND}	ground current		-50	-	mA	
T _{stg}	storage temperature		-65	+150	°C	
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C				
		TSSOP5, XSON6, X2SON5 and WLCSP6 package	[2]	-	250 mW	
		X2SON4 package	[3]	-	150 mW	

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP5 packages: above 87.5 °C the value of P_{tot} derates linearly with 4.0 mW/K.

For XSON6 and X2SON5 packages: above 118 °C the value of P_{tot} derates linearly with 7.8 mW/K.

For WLCSP6 package: above 102.5 °C the value of P_{tot} derates linearly with 5.3 mW/K.

[3] For X2SON4 packages: above 57 °C the value of P_{tot} derates linearly with 1.7 mW/K.

9 Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		0.8	3.6	V
V _I	input voltage		0	3.6	V
V _O	output voltage	Active mode	0	V _{CC}	V
		Power-down mode; V _{CC} = 0 V	0	3.6	V
T _{amb}	ambient temperature		-40	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 0.8 V to 3.6 V	0	200	ns/V

10 Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = 25 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 0.8 V	0.70 × V _{CC}	-	-	V
		V _{CC} = 0.9 V to 1.95 V	0.65 × V _{CC}	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.6	-	-	V
		V _{CC} = 3.0 V to 3.6 V	2.0	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 0.8 V	-	-	0.30 × V _{CC}	V
		V _{CC} = 0.9 V to 1.95 V	-	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 3.0 V to 3.6 V	-	-	0.9	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.1	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.75 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	1.11	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.32	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	2.05	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.9	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.72	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.6	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.1	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.3 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.31	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.31	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.31	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.44	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.31	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.44	V
I _I	input leakage current	V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V	-	-	±0.1	µA
I _{OFF}	power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V	-	-	±0.2	µA
ΔI _{OFF}	additional power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V to 0.2 V	-	-	±0.2	µA

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
I_{CC}	supply current	$V_I = GND$ or $V_{CC} = 0 A$; $V_{CC} = 0.8 V$ to $3.6 V$	-	-	0.5	μA	
ΔI_{CC}	additional supply current	$V_I = V_{CC} - 0.6 V$; $I_O = 0 A$; $V_{CC} = 3.3 V$	[1]	-	-	40	μA
C_I	input capacitance	$V_{CC} = 0 V$ to $3.6 V$; $V_I = GND$ or V_{CC}	-	0.8	-	pF	
C_O	output capacitance	$V_O = GND$; $V_{CC} = 0 V$	-	1.7	-	pF	
$T_{amb} = -40^\circ C$ to $+85^\circ C$							
V_{IH}	HIGH-level input voltage	$V_{CC} = 0.8 V$	$0.70 \times V_{CC}$	-	-	V	
		$V_{CC} = 0.9 V$ to $1.95 V$	$0.65 \times V_{CC}$	-	-	V	
		$V_{CC} = 2.3 V$ to $2.7 V$	1.6	-	-	V	
		$V_{CC} = 3.0 V$ to $3.6 V$	2.0	-	-	V	
V_{IL}	LOW-level input voltage	$V_{CC} = 0.8 V$	-	-	$0.30 \times V_{CC}$	V	
		$V_{CC} = 0.9 V$ to $1.95 V$	-	-	$0.35 \times V_{CC}$	V	
		$V_{CC} = 2.3 V$ to $2.7 V$	-	-	0.7	V	
		$V_{CC} = 3.0 V$ to $3.6 V$	-	-	0.9	V	
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}					
		$I_O = -20 \mu A$; $V_{CC} = 0.8 V$ to $3.6 V$	$V_{CC} - 0.1$	-	-	V	
		$I_O = -1.1 mA$; $V_{CC} = 1.1 V$	$0.7 \times V_{CC}$	-	-	V	
		$I_O = -1.7 mA$; $V_{CC} = 1.4 V$	1.03	-	-	V	
		$I_O = -1.9 mA$; $V_{CC} = 1.65 V$	1.30	-	-	V	
		$I_O = -2.3 mA$; $V_{CC} = 2.3 V$	1.97	-	-	V	
		$I_O = -3.1 mA$; $V_{CC} = 2.3 V$	1.85	-	-	V	
		$I_O = -2.7 mA$; $V_{CC} = 3.0 V$	2.67	-	-	V	
		$I_O = -4.0 mA$; $V_{CC} = 3.0 V$	2.55	-	-	V	
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}					
		$I_O = 20 \mu A$; $V_{CC} = 0.8 V$ to $3.6 V$	-	-	0.1	V	
		$I_O = 1.1 mA$; $V_{CC} = 1.1 V$	-	-	$0.3 \times V_{CC}$	V	
		$I_O = 1.7 mA$; $V_{CC} = 1.4 V$	-	-	0.37	V	
		$I_O = 1.9 mA$; $V_{CC} = 1.65 V$	-	-	0.35	V	
		$I_O = 2.3 mA$; $V_{CC} = 2.3 V$	-	-	0.33	V	
		$I_O = 3.1 mA$; $V_{CC} = 2.3 V$	-	-	0.45	V	
		$I_O = 2.7 mA$; $V_{CC} = 3.0 V$	-	-	0.33	V	
		$I_O = 4.0 mA$; $V_{CC} = 3.0 V$	-	-	0.45	V	
I_I	input leakage current	$V_I = GND$ to $3.6 V$; $V_{CC} = 0 V$ to $3.6 V$	-	-	± 0.5	μA	
I_{OFF}	power-off leakage current	V_I or $V_O = 0 V$ to $3.6 V$; $V_{CC} = 0 V$	-	-	± 0.5	μA	

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
ΔI_{OFF}	additional power-off leakage current	V_I or $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V to 0.2 V	-	-	± 0.6	μA
I_{CC}	supply current	$V_I = GND$ or V_{CC} ; $I_O = 0$ A; $V_{CC} = 0.8$ V to 3.6 V	-	-	0.9	μA
ΔI_{CC}	additional supply current	$V_I = V_{CC} - 0.6$ V; $I_O = 0$ A; $V_{CC} = 3.3$ V	[1]	-	50	μA
$T_{amb} = -40$ °C to +125 °C						
V_{IH}	HIGH-level input voltage	$V_{CC} = 0.8$ V	$0.75 \times V_{CC}$	-	-	V
		$V_{CC} = 0.9$ V to 1.95 V	$0.70 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3$ V to 2.7 V	1.6	-	-	V
		$V_{CC} = 3.0$ V to 3.6 V	2.0	-	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 0.8$ V	-	-	$0.25 \times V_{CC}$	V
		$V_{CC} = 0.9$ V to 1.95 V	-	-	$0.30 \times V_{CC}$	V
		$V_{CC} = 2.3$ V to 2.7 V	-	-	0.7	V
		$V_{CC} = 3.0$ V to 3.6 V	-	-	0.9	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		$I_O = -20 \mu A$; $V_{CC} = 0.8$ V to 3.6 V	$V_{CC} - 0.11$	-	-	V
		$I_O = -1.1$ mA; $V_{CC} = 1.1$ V	$0.6 \times V_{CC}$	-	-	V
		$I_O = -1.7$ mA; $V_{CC} = 1.4$ V	0.93	-	-	V
		$I_O = -1.9$ mA; $V_{CC} = 1.65$ V	1.17	-	-	V
		$I_O = -2.3$ mA; $V_{CC} = 2.3$ V	1.77	-	-	V
		$I_O = -3.1$ mA; $V_{CC} = 2.3$ V	1.67	-	-	V
		$I_O = -2.7$ mA; $V_{CC} = 3.0$ V	2.40	-	-	V
		$I_O = -4.0$ mA; $V_{CC} = 3.0$ V	2.30	-	-	V

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		$I_O = 20 \mu A; V_{CC} = 0.8 V$ to $3.6 V$	-	-	0.11	V
		$I_O = 1.1 mA; V_{CC} = 1.1 V$	-	-	$0.33 \times V_{CC}$	V
		$I_O = 1.7 mA; V_{CC} = 1.4 V$	-	-	0.41	V
		$I_O = 1.9 mA; V_{CC} = 1.65 V$	-	-	0.39	V
		$I_O = 2.3 mA; V_{CC} = 2.3 V$	-	-	0.36	V
		$I_O = 3.1 mA; V_{CC} = 2.3 V$	-	-	0.50	V
		$I_O = 2.7 mA; V_{CC} = 3.0 V$	-	-	0.36	V
		$I_O = 4.0 mA; V_{CC} = 3.0 V$	-	-	0.50	V
I_I	input leakage current	$V_I = GND$ to $3.6 V$; $V_{CC} = 0 V$ to $3.6 V$	-	-	± 0.75	μA
I_{OFF}	power-off leakage current	V_I or $V_O = 0 V$ to $3.6 V$; $V_{CC} = 0 V$	-	-	± 0.75	μA
ΔI_{OFF}	additional power-off leakage current	V_I or $V_O = 0 V$ to $3.6 V$; $V_{CC} = 0 V$ to $0.2 V$	-	-	± 0.75	μA
I_{CC}	supply current	$V_I = GND$ or V_{CC} ; $I_O = 0 A$; $V_{CC} = 0.8 V$ to $3.6 V$	-	-	1.4	μA
ΔI_{CC}	additional supply current	$V_I = V_{CC} - 0.6 V$; $I_O = 0 A$; $V_{CC} = 3.3 V$	[1]	-	75	μA

[1] One input at $V_{CC} - 0.6 V$, other input at V_{CC} or GND.

11 Dynamic characteristics

Table 8. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 11](#).

Symbol	Parameter	Conditions	T _{amb} = 25 °C			T _{amb} = -40 °C to +125 °C			Unit
			Min	Typ ^[1]	Max	Min	Max (85 °C)	Min	
C_L = 5 pF									
t _{pd}	propagation delay	A to Y; see Figure 10 [2]							
		V _{CC} = 0.8 V	-	15.0	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	2.6	4.7	9.2	2.0	10.0	2.0	11.0
		V _{CC} = 1.4 V to 1.6 V	2.1	3.4	5.7	1.6	6.5	1.6	7.2
		V _{CC} = 1.65 V to 1.95 V	1.8	2.9	4.5	1.4	5.2	1.4	5.8
		V _{CC} = 2.3 V to 2.7 V	1.5	2.3	3.5	1.2	4.2	1.2	4.6
		V _{CC} = 3.0 V to 3.6 V	1.4	2.1	3.2	1.0	3.8	1.0	4.2
C_L = 10 pF									
t _{pd}	propagation delay	A to Y; see Figure 10 [2]							
		V _{CC} = 0.8 V	-	18.4	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	3.2	5.6	10.9	2.3	11.8	2.3	13.1
		V _{CC} = 1.4 V to 1.6 V	2.6	4.1	6.7	1.9	7.7	1.9	8.5
		V _{CC} = 1.65 V to 1.95 V	2.3	3.4	5.3	1.7	6.2	1.7	6.9
		V _{CC} = 2.3 V to 2.7 V	2.0	2.9	4.2	1.5	5.0	1.5	5.5
		V _{CC} = 3.0 V to 3.6 V	1.7	2.6	3.8	1.4	4.6	1.4	5.1
C_L = 15 pF									
t _{pd}	propagation delay	A to Y; see Figure 10 [2]							
		V _{CC} = 0.8 V	-	21.9	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	3.6	6.4	12.6	2.6	13.8	2.6	15.2
		V _{CC} = 1.4 V to 1.6 V	3.0	4.6	7.6	2.2	8.9	2.2	9.8
		V _{CC} = 1.65 V to 1.95 V	2.6	3.9	6.0	2.0	7.2	2.0	7.9
		V _{CC} = 2.3 V to 2.7 V	2.3	3.3	4.8	1.8	5.7	1.8	6.3
		V _{CC} = 3.0 V to 3.6 V	2.1	3.1	4.2	1.6	5.0	1.6	5.5

Symbol	Parameter	Conditions	T _{amb} = 25 °C			T _{amb} = -40 °C to +125 °C			Unit
			Min	Typ ^[1]	Max	Min	Max (85 °C)	Min	
C_L = 30 pF									
t _{pd}	propagation delay	A to Y; see Figure 10 [2]							
		V _{CC} = 0.8 V	-	32.1	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	4.8	8.7	16.3	3.6	18.9	3.6	20.8 ns
		V _{CC} = 1.4 V to 1.6 V	4.0	6.2	10.3	3.4	12.2	3.4	13.4 ns
		V _{CC} = 1.65 V to 1.95 V	3.6	5.2	8.1	3.2	9.8	3.2	10.8 ns
		V _{CC} = 2.3 V to 2.7 V	3.0	4.4	6.4	2.7	7.7	2.7	8.5 ns
		V _{CC} = 3.0 V to 3.6 V	2.9	4.2	5.6	2.5	6.5	2.5	7.2 ns
C _{PD}	power dissipation capacitance	V _I = GND to V _{CC} ; f _i = 1 MHz [3]							
		V _{CC} = 0.8 V	-	2.5	-	-	-	-	pF
		V _{CC} = 1.1 V to 1.3 V	-	2.6	-	-	-	-	pF
		V _{CC} = 1.4 V to 1.6 V	-	2.7	-	-	-	-	pF
		V _{CC} = 1.65 V to 1.95 V	-	2.9	-	-	-	-	pF
		V _{CC} = 2.3 V to 2.7 V	-	3.4	-	-	-	-	pF
		V _{CC} = 3.0 V to 3.6 V	-	4.0	-	-	-	-	pF

[1] All typical values are measured at nominal V_{CC}.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μ W).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

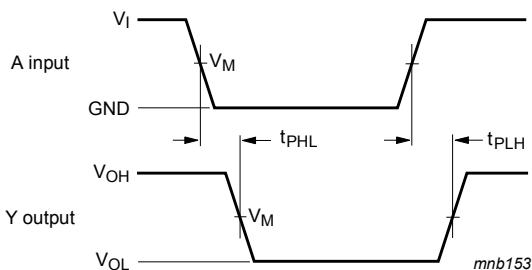
C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

$$\sum(C_L \times V_{CC}^2 \times f_o) = \text{sum of outputs.}$$

11.1 Waveform and test circuit



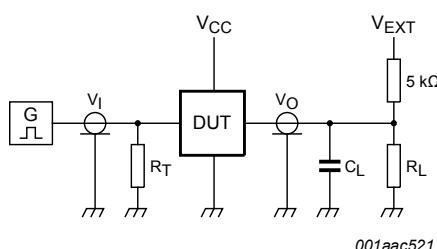
Measurement points are given in [Table 9](#).

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Figure 10. The data input (A) to output (Y) propagation delays

Table 9. Measurement points

Supply voltage	Output	Input		
V_{CC}	V_M	V_M	V_I	$t_r = t_f$
0.8 V to 3.6 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{CC}	$\leq 3.0 \text{ ns}$



Test data is given in [Table 10](#).

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to the output impedance Z_0 of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

Figure 11. Test circuit for measuring switching times

Table 10. Test data

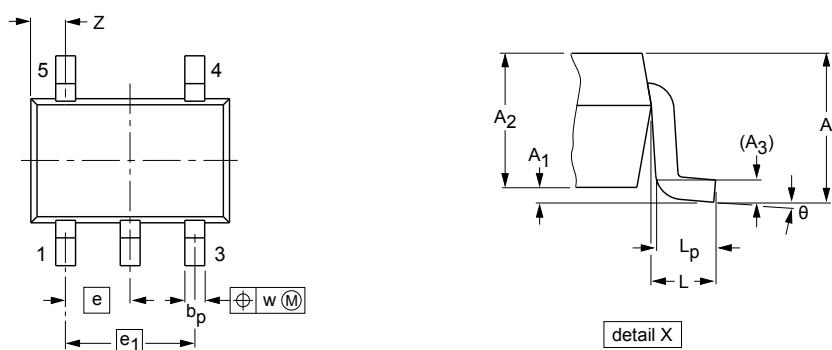
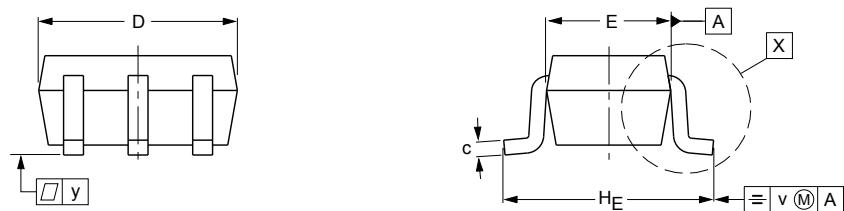
Supply voltage	Load	V_{EXT}
V_{CC}	C_L	R_L [1]
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 k Ω or 1 M Ω

[1] For measuring enable and disable times $R_L = 5 \text{ k}\Omega$, for measuring propagation delays, setup and hold times and pulse width $R_L = 1 \text{ M}\Omega$.

12 Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1



0 1.5 3 mm
scale

DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	H _E	L	L _p	v	w	y	Z ⁽¹⁾	θ	
mm	1.1	0.10	1.0	0.8	0.15	0.30	0.25	2.25	1.35	0.65	1.3	2.25	0.425	0.46	0.3	0.1	0.1	0.60	7°
						0.15	1.85	1.15			2.0	2.0	0.21				0.15	0°	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT353-1		MO-203	SC-88A			00-09-01 03-02-19

Figure 12. Package outline SOT353-1 (TSSOP5)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

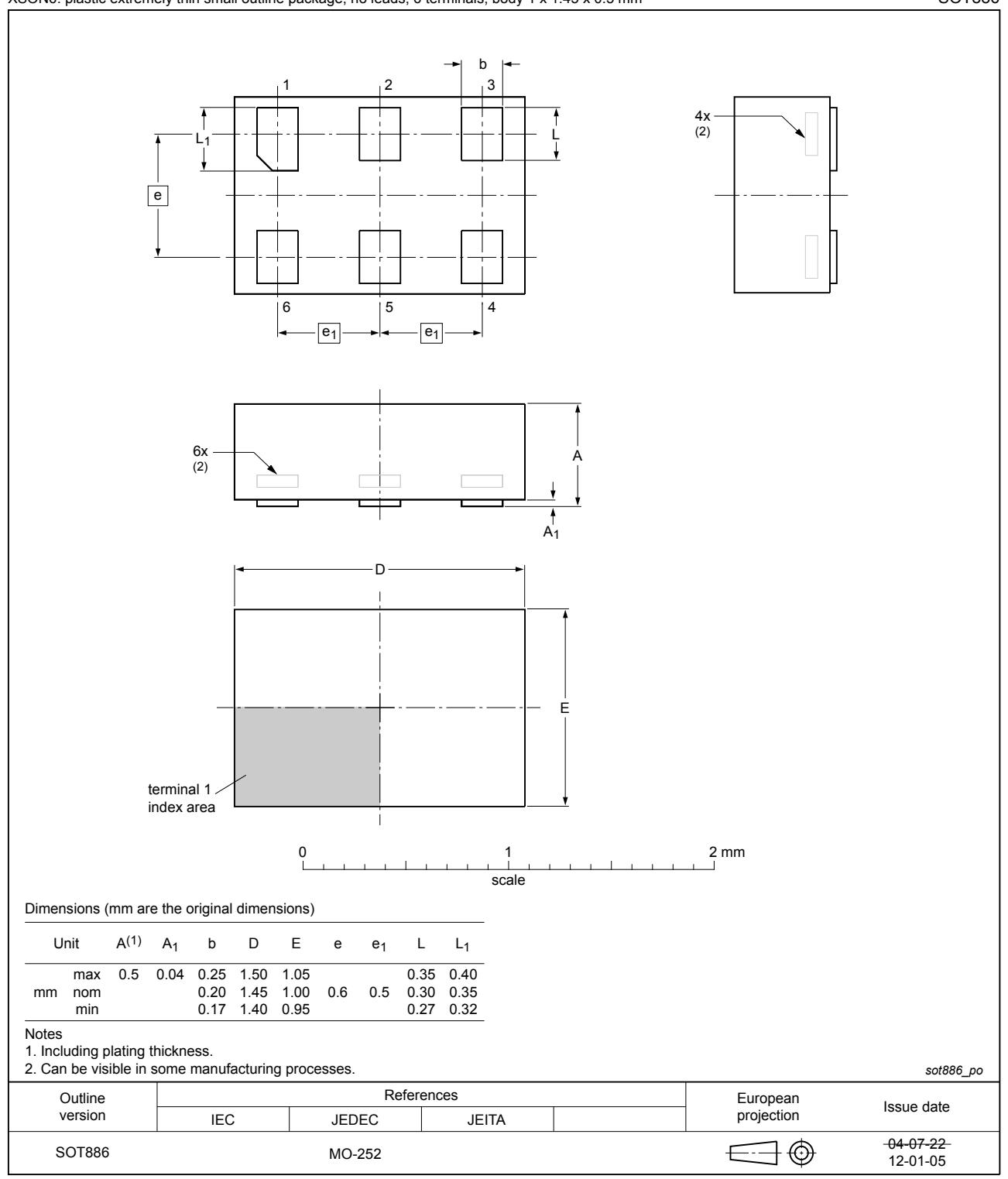
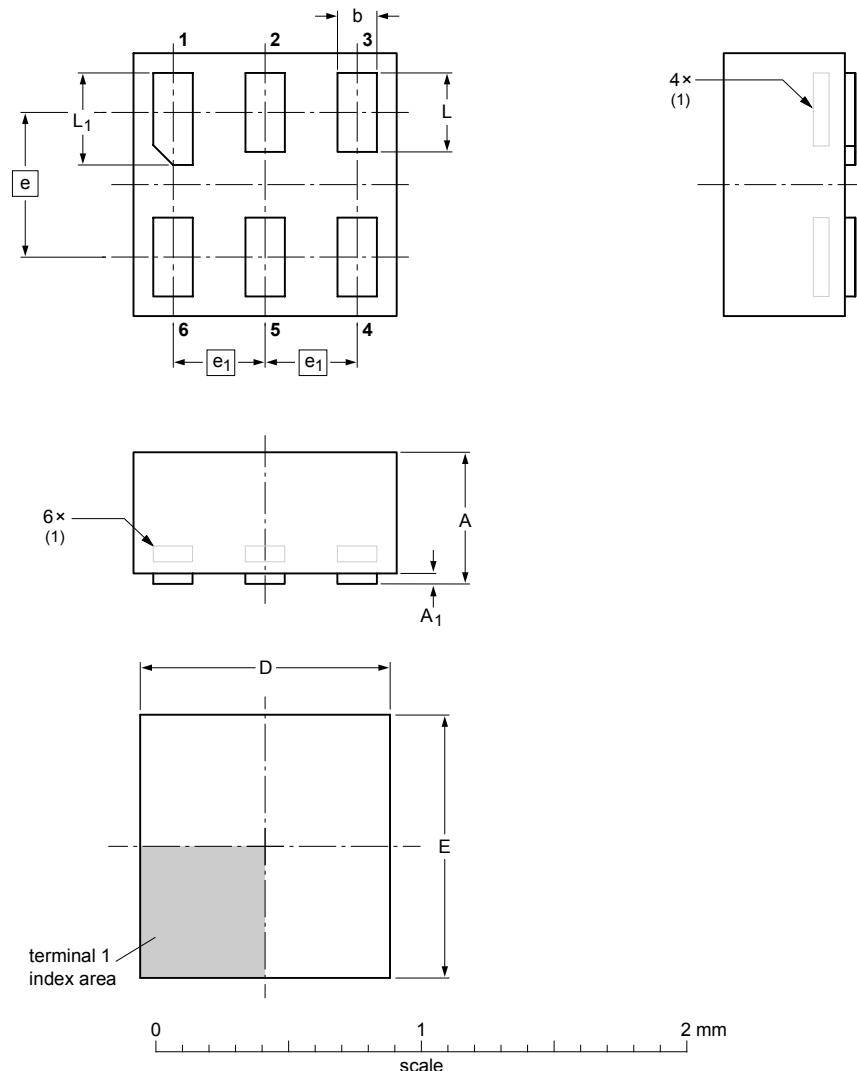


Figure 13. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body $1 \times 1 \times 0.5$ mm

SOT891



DIMENSIONS (mm are the original dimensions)

UNIT	A max	A1 max	b	D	E	e	e ₁	L	L ₁
mm	0.5	0.04	0.20 0.12	1.05 0.95	1.05 0.95	0.55	0.35	0.35 0.27	0.40 0.32

Note

1. Can be visible in some manufacturing processes.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT891						-05-04-06 07-05-15

Figure 14. Package outline SOT891 (XSON6)

XSON6: extremely thin small outline package; no leads;
6 terminals; body 0.9 x 1.0 x 0.35 mm

SOT1115

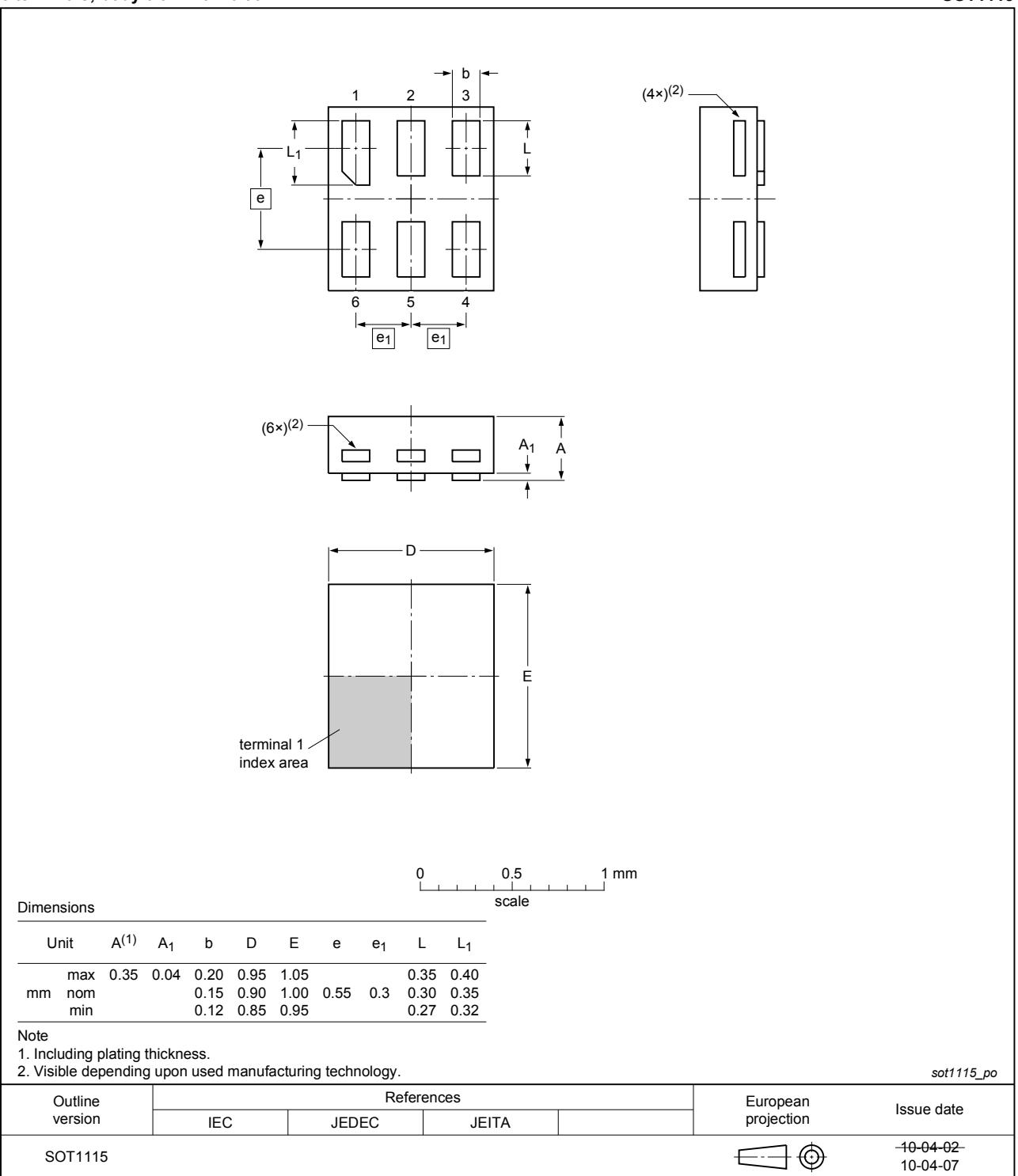
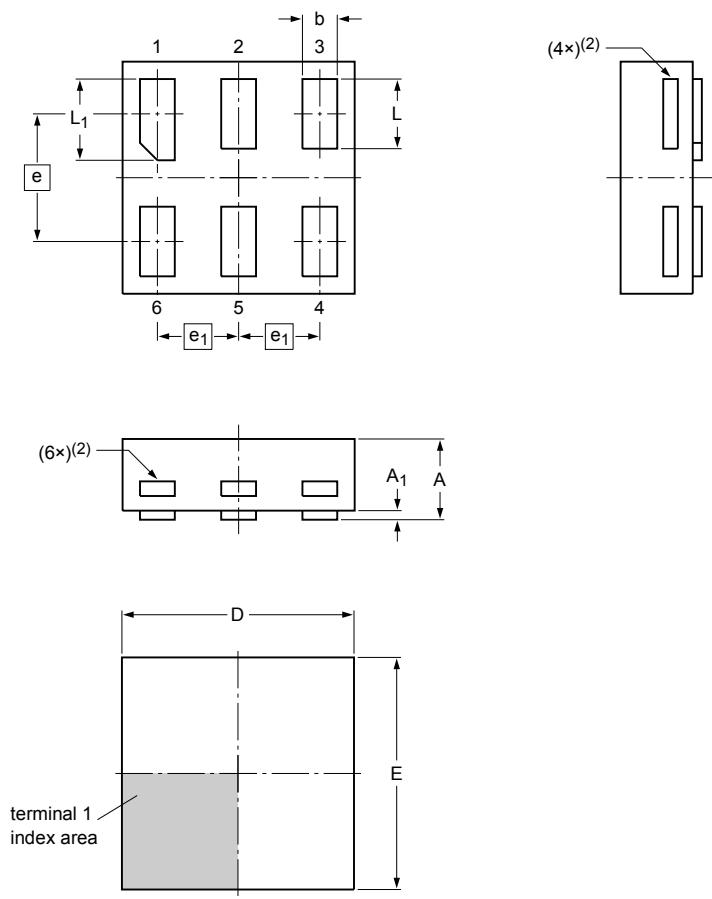


Figure 15. Package outline SOT1115 (XSON6)

XSON6: extremely thin small outline package; no leads;
6 terminals; body 1.0 x 1.0 x 0.35 mm

SOT1202



Dimensions

Unit	A ⁽¹⁾	A ₁	b	D	E	e	e ₁	L	L ₁
mm	max	0.35	0.04	0.20	1.05	1.05		0.35	0.40
mm	nom			0.15	1.00	1.00	0.55	0.35	0.35
mm	min			0.12	0.95	0.95		0.27	0.32

Note

1. Including plating thickness.
2. Visible depending upon used manufacturing technology.

sot1202_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1202					-10-04-02- 10-04-06

Figure 16. Package outline SOT1202 (XSON6)

X2SON5: plastic thermal enhanced extremely thin small outline package; no leads;
5 terminals; body 0.8 x 0.8 x 0.35 mm

SOT1226

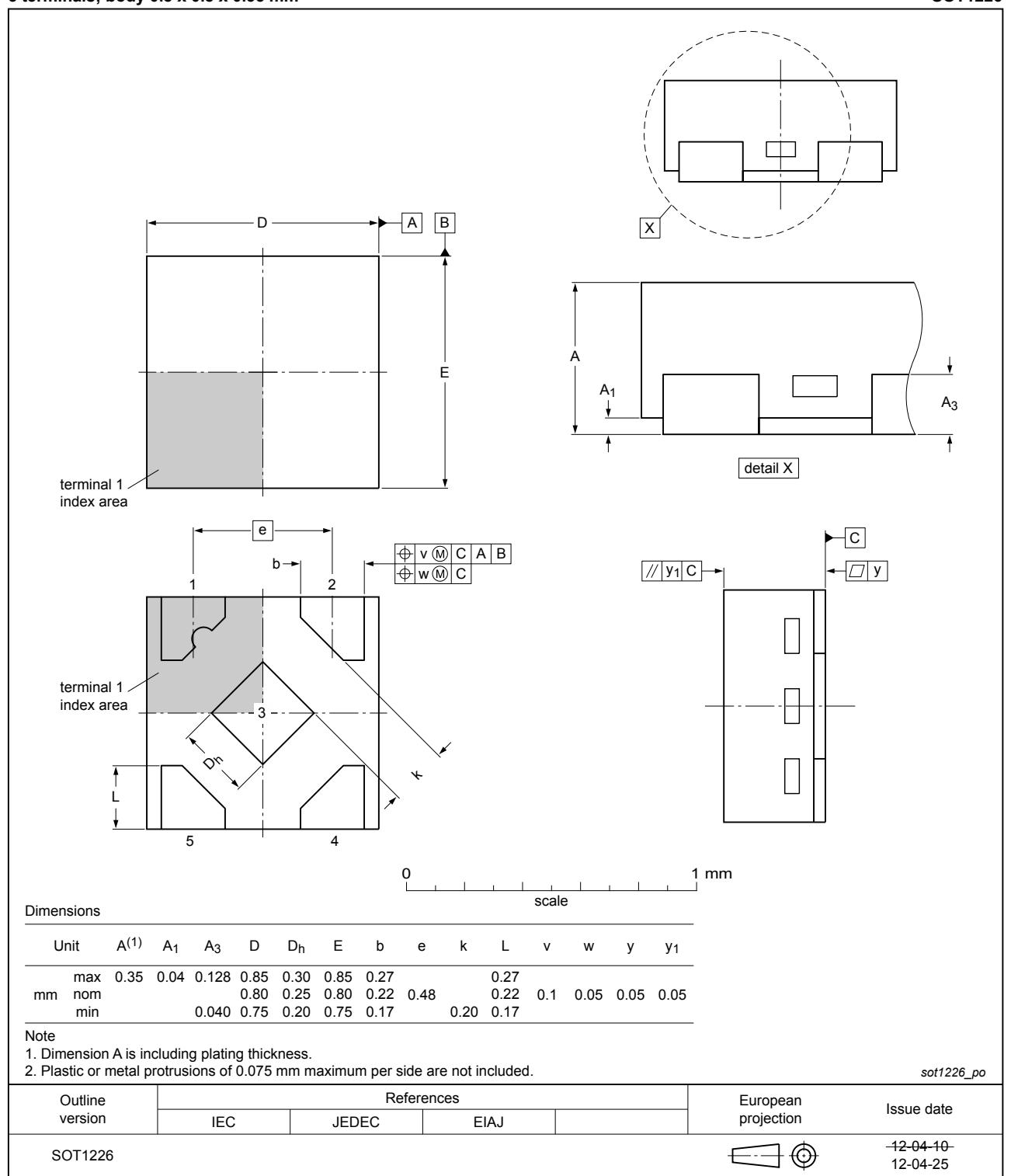
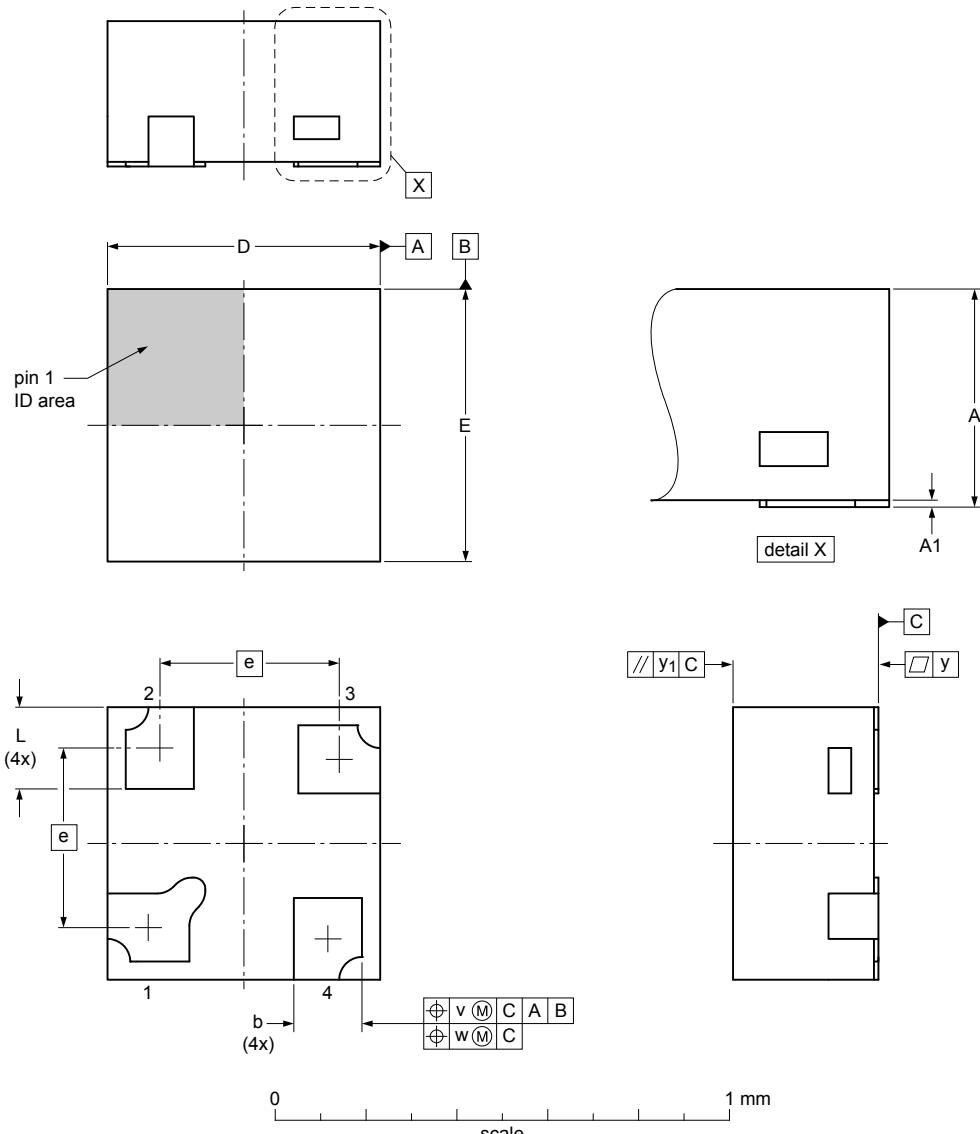


Figure 17. Package outline SOT1226 (X2SON5)

X2SON4: plastic thermal enhanced extremely thin small outline package; no leads;
4 terminals; body 0.6 x 0.6 x 0.32 mm

SOT1269-2



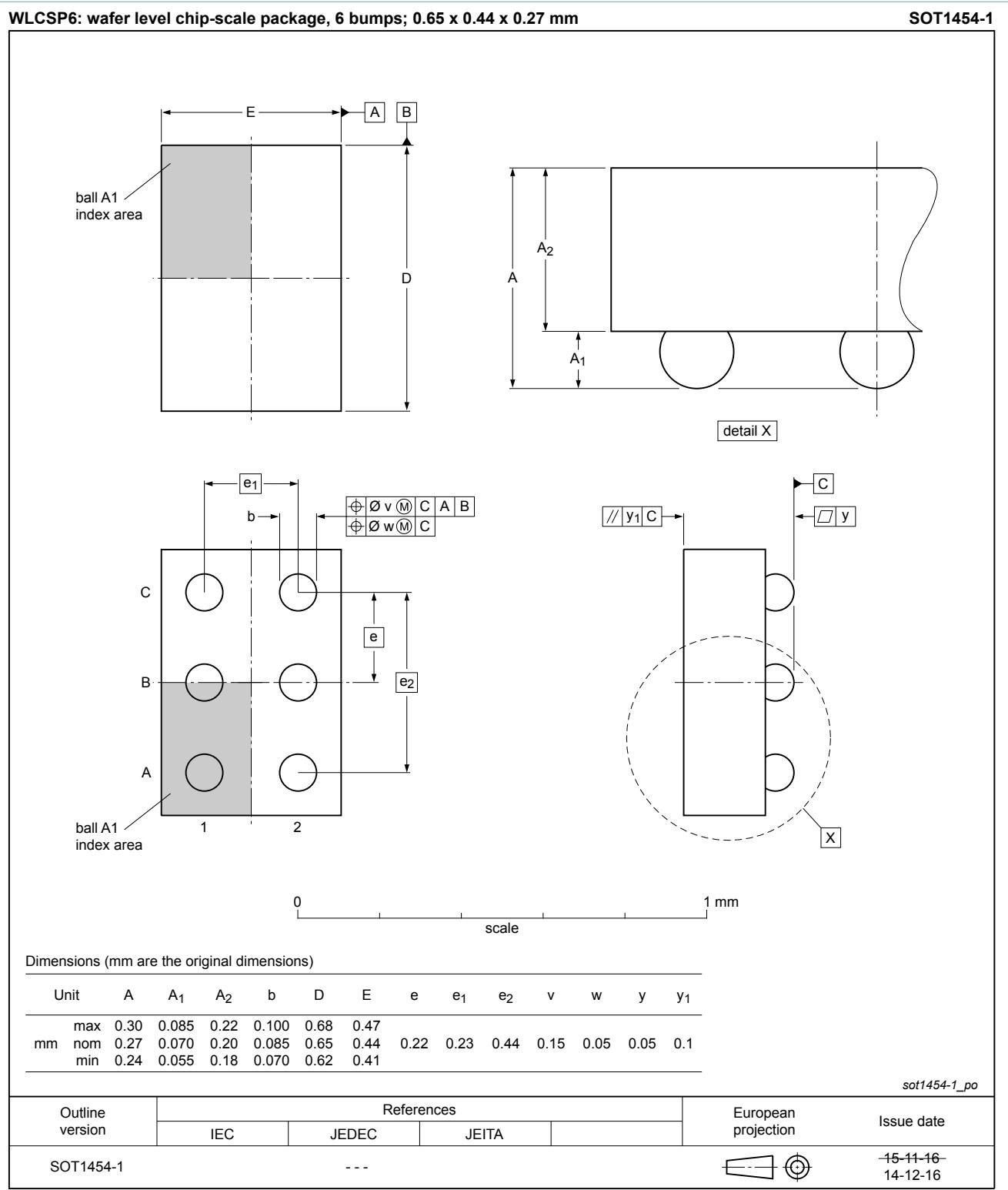
Dimensions (mm are the original dimensions)

Unit	A	A ₁	D	E	b	e	L	v	w	y	y ₁
max	0.35	0.04	0.65	0.65	0.20		0.23				
mm nom	0.32	0.02	0.60	0.60	0.15	0.40	0.18	0.10	0.05	0.05	0.05
min	0.30	0.00	0.55	0.55	0.10		0.13				

sot1269-2_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1269-2	---				17-04-07 17-06-30

Figure 18. Package outline SOT1269-2 (X2SON4)

**Figure 19. Package outline SOT1454-1 (WLCSP6)**

13 Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

14 Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP1G34 v.8	20180608	Product data sheet	-	74AUP1G34 v.7
Modifications:	<ul style="list-style-type: none"> Added type number 74AUP1G34GX4 (SOT1269-2) 			
74AUP1G34 v.7	20170328	Product data sheet	-	74AUP1G34 v.6
Modifications:	<ul style="list-style-type: none"> Added type number 74AUP1G34UK (SOT1454-1/WLCSP6) 			
74AUP1G34 v.6	20120628	Product data sheet	-	74AUP1G34 v.5
Modifications:	<ul style="list-style-type: none"> Added type number 74AUP1G34GX (SOT1226) Package outline drawing of SOT886 (Figure 13) modified. 			
74AUP1G34 v.5	20111128	Product data sheet	-	74AUP1G34 v.4
Modifications:	<ul style="list-style-type: none"> Legal pages updated. 			
74AUP1G34 v.4	20100714	Product data sheet	-	74AUP1G34 v.3
74AUP1G34 v.3	20080814	Product data sheet	-	74AUP1G34 v.2
74AUP1G34 v.2	20060704	Product data sheet	-	74AUP1G34 v.1
74AUP1G34 v.1	20050804	Product data sheet	-	-

15 Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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